

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-162691

(43)Date of publication of application : 20.06.1997

(51)Int.Cl.

H03H 9/25  
H01L 27/04  
H01L 21/822  
H03H 3/08  
H03H 9/145

(21)Application number : 07-325291

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(22)Date of filing : 14.12.1995

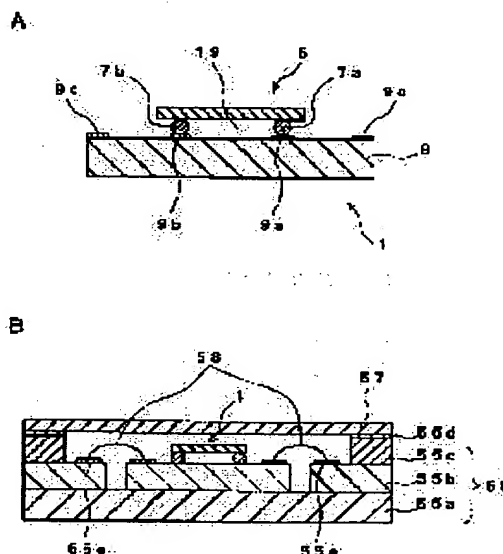
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## (54) DEVICE HAVING SURFACE ACOUSTIC WAVE ELEMENT AND ITS MANUFACTURE

(57)Abstract:

**PROBLEM TO BE SOLVED:** To provide the surface acoustic wave element to be miniaturized with high reliability.

**SOLUTION:** A SAW chip 5 is mounted above an LSI 9 via bumps 7a, 7b. Input output electrodes and external connection electrodes 9a, 9b are connected electrically by the bumps 7a, 7b. The SAW chip and the LSI 1 once manufactured separately are structured to be a 2-stage stack structure, then miniaturization is attained without the use of a piezoelectric thin film forming technology. Moreover, no bonding wire is required between the SAW chip and the LSI 1 by using the bumps.



## LEGAL STATUS

[Date of request for examination] 21.11.2002

[Date of sending the examiner's decision of rejection] 27.10.2003

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's

decision of rejection]

[Date of extinction of right]

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